Supplier Name: **Texas Instruments Inc. (DUNS# 00-732-1904)**
Contact Info: ti.com/support
Form/Declaration Type: **Distribute - RoHS and IEC 62474 DB**
Created on: **06/04/2022**

Details for "OMAP5912ZVLR"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package | Pins	Package body size (mm)	Total device mass (mg)*
OMAP5912ZVLR	SNAGCU	Level-3-260C-168 HR	TI PHILIPPINES A/T	ZVL | 289	12.1x12.1x0.89	307.1

***Total Device Mass**
The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

				Homogeneous Material Level		Component Level	
Component	**Substance**	**CAS Number**	**Amount (mg)**	**Percentage %**	**ppm**	**Percentage %**	**ppm**
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	1.499124	97.534957	975350	0.488162	4882
Nickel and Its Alloys	Nickel	7440-02-0	0.000008	0.00052	5	0.000003	0
Not Categorized	Proprietary Materials		0.000169	0.010995	110	0.000055	1
Precious Metals	Gold	7440-57-5	0.00079	0.051398	514	0.000257	3
Precious Metals	Palladium	7440-05-3	0.036876	2.399201	23992	0.012008	120
Precious Metals	Silver	7440-22-4	0.000045	0.002928	29	0.000015	0
Sub-Total			**1.537012**	**100**	**1000000**	**0.500499**	**5005**
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	10.514964	81.999999	820000	3.424002	34240
Thermoplastics	Epoxy	85954-11-6	2.308163	18.000001	180000	0.75161	7516
Sub-Total			**12.823127**	**100**	**1000000**	**4.175612**	**41756**
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	135.699438	85	850000	44.187987	441880
Other Nonferrous Metals and Alloys	Metal Oxide	Trade Secret	1.596464	1	10000	0.519859	5199
Other Plastics and Rubber	Carbon Black	1333-86-4	0.399116	0.25	2500	0.129965	1300
Thermoplastics	Epoxy	85954-11-6	21.95138	13.75	137500	7.148057	71481
Sub-Total			**159.646398**	**100**	**1000000**	**51.985867**	**519859**
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	40.299842	100	1000000	13.122891	131229
Sub-Total			**40.299842**	**100**	**1000000**	**13.122891**	**131229**
Solder Ball							
Copper and Its Alloys	Copper	7440-50-8	0.150297	0.5	5000	0.048941	489
Nickel and Its Alloys	Nickel	7440-02-0	0.01503	0.050001	500	0.004894	49
Other Nonferrous Metals and Alloys	Tin	7440-31-5	29.533355	98.249998	982500	9.616985	96170
Precious Metals	Silver	7440-22-4	0.360713	1.200001	12000	0.117459	1175
Sub-Total			**30.059395**	**100**	**1000000**	**9.78828**	**97883**
Substrate							
Ceramics / Glass	Woven Glass Fiber	65997-17-3	20.064611	31.985673	319857	6.533666	65337
Copper and Its Alloys	Copper	7440-50-8	21.695992	34.586313	345863	7.064894	70649
Nickel and Its Alloys	Nickel	7440-02-0	0.01397	0.02227	223	0.004549	45
Not Categorized	Proprietary Filler		0.983174	1.567311	15673	0.320152	3202
Other Inorganic Materials	Silica	7631-86-9	0.983174	1.567311	15673	0.320152	3202
Other Nonferrous Metals and Alloys	Barium Sulfate	7727-43-7	0.983174	1.567311	15673	0.320152	3202
Other Plastics and Rubber	Phthalocyanine Blue	147-14-8	0.032061	0.05111	511	0.01044	104
Precious Metals	Gold	7440-57-5	0.236429	0.376899	3769	0.076989	770
Thermoplastics	Epoxy	85954-11-6	17.737409	28.275802	282758	5.775856	57759
Sub-Total			**62.729994**	**100**	**1000000**	**20.426851**	**204269**
Total			307.095768			100	1000000

Important Note
The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
See Glossary of Terms for more details.

Important Part Information
There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology
For an explanation of the methods used to determine material weights, See Product Content Methodology

Material Declaration Certificate for Semiconductor IC Packaged Products

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For additional information, please contact TI customer support.

Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality
For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

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Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.